

SOT728-1

plastic low profile ball grid array package; 324 balls; body 19 x 19 x 1.05 mm

14 June 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LBGA324
Package type industry code	LBGA324
Package style descriptive code	LBGA (low profile ball grid array)
Package body material type	P (plastic)
JEDEC package outline code	MO-192
Mounting method type	S (surface mount)
Issue date	1-11-2001

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		18.8	-	19	19.2	mm
E	package width		18.8	-	19	19.2	mm
A	seated height		-	-	1.65	1.65	mm
A ₂	package height		0.95	-	1.05	1.2	mm
e	nominal pitch		-	-	-	-	
n ₂	actual quantity of termination		-	-	324	-	



2. Package outline

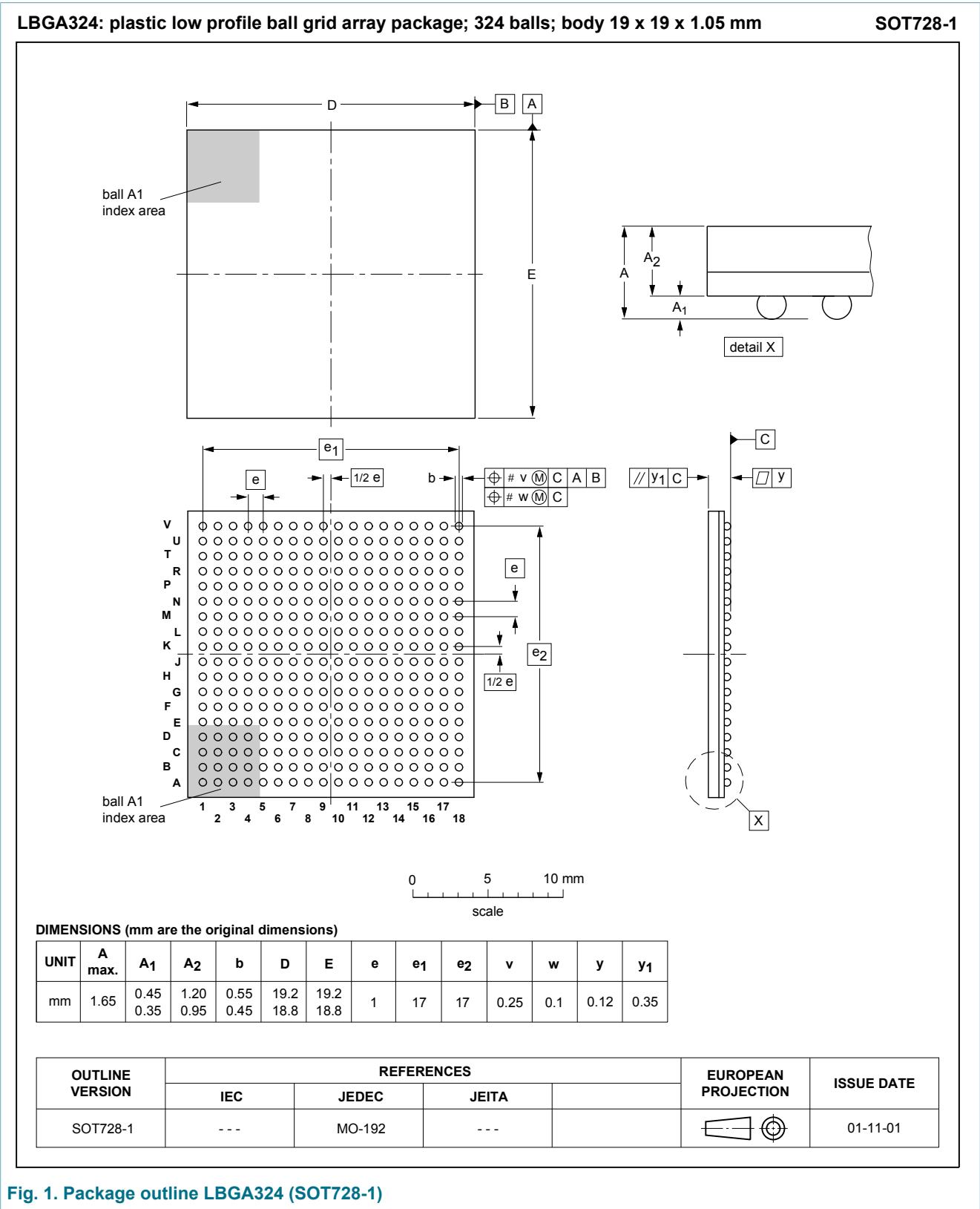


Fig. 1. Package outline LPGA324 (SOT728-1)

3. Soldering

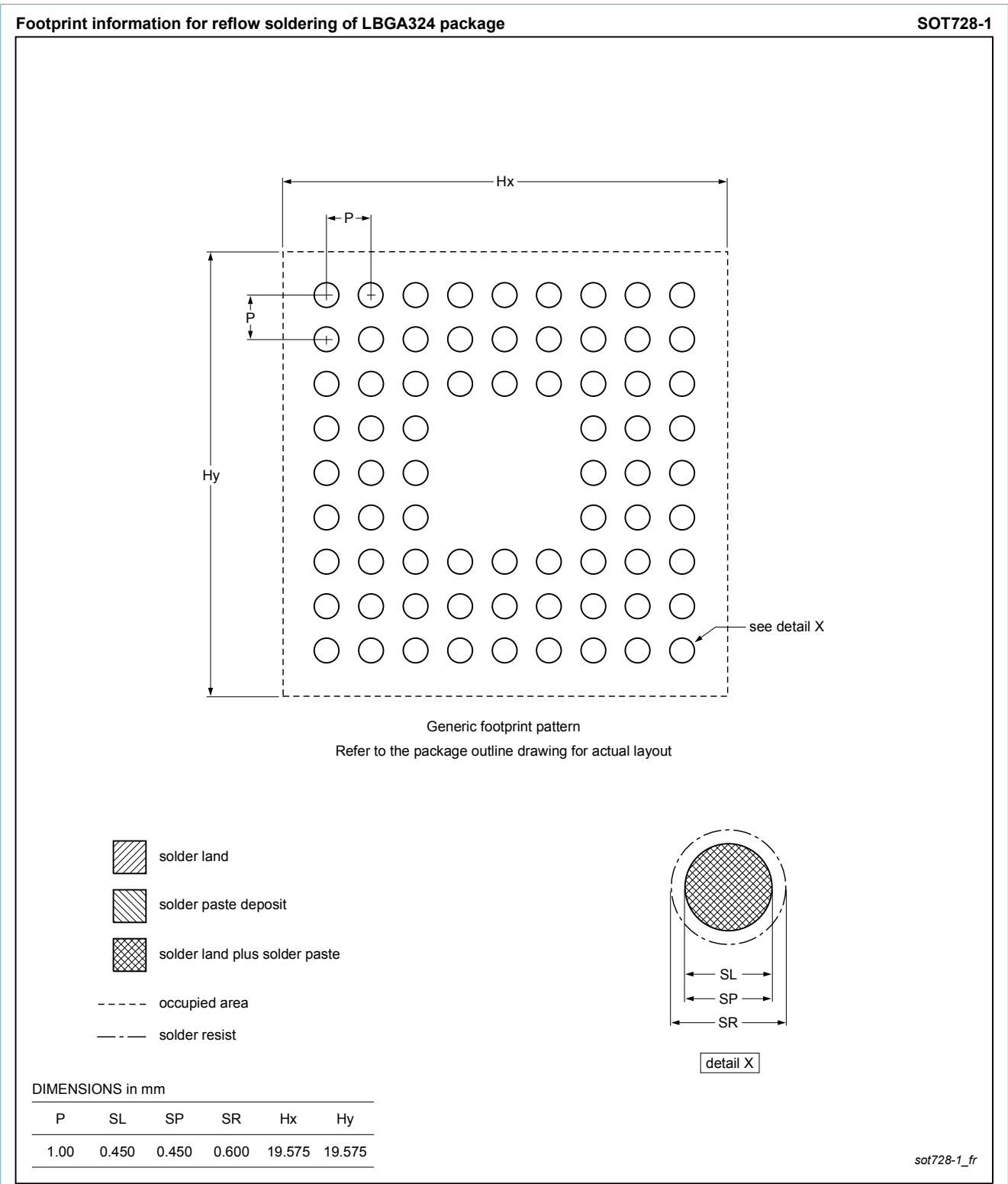


Fig. 2. Reflow soldering footprint for LBGA324 (SOT728-1)

4. Legal information

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